

# Depleted Monolithic Active Pixel Sensors (WP5) - Summary

*F. Hügging (University of Bonn)*

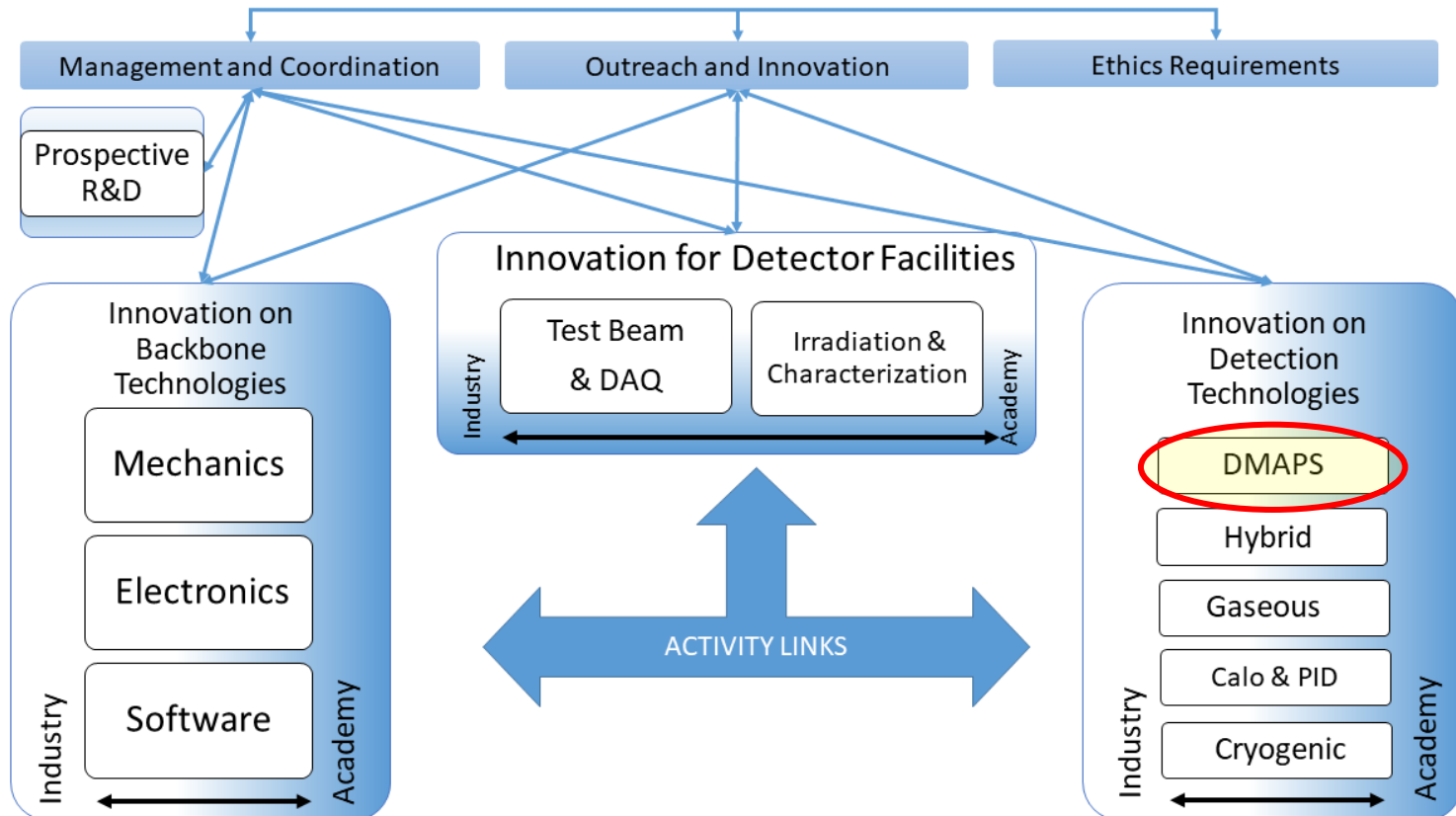
The 2023 International Workshop on the High  
Energy Circular Electron Positron Collider



This project has received funding from the European Union's Horizon 2020 research and innovation programme under grant agreement No 101004761.

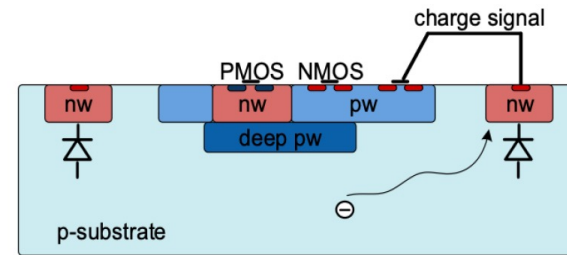
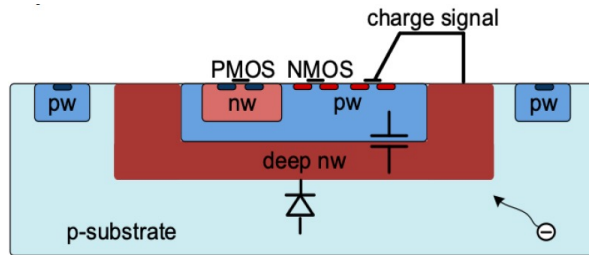
- To explore applications of novel technologies such as **integrated CMOS sensors**, additive manufacturing or machine learning, and to assess their performance for the **challenging needs of future or upgraded HEP experiments**.

• ...



- ❑ **7 projects** are (partially, not exclusively) supported by the AIDAInnova framework using 4 different processes provided by 2 foundries: **LFoundry** (Wuxi Xichanweixin Semiconductor) and **TowerJazz** → Tower Semiconductor (Intel as of 2022)
- ❑ All developments have samples, characterisation in full swing

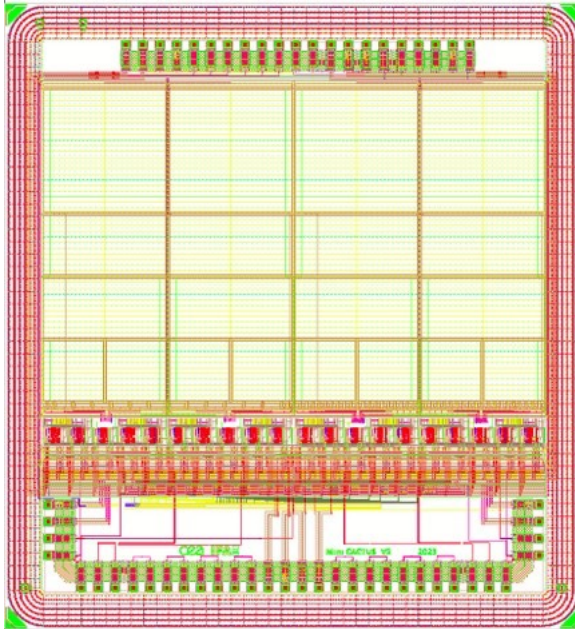
large  
electrode  
(radhard)



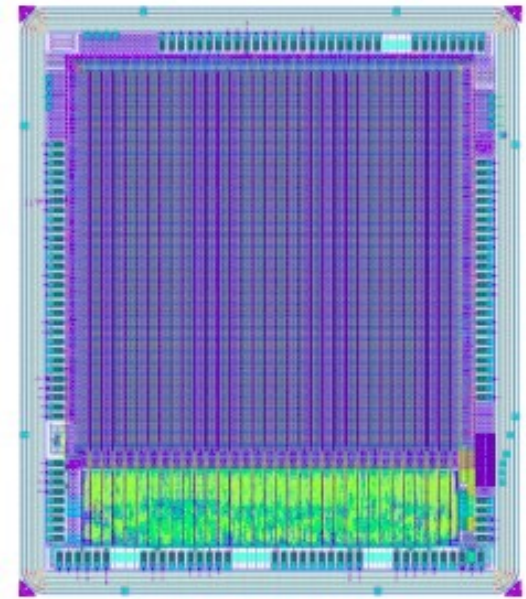
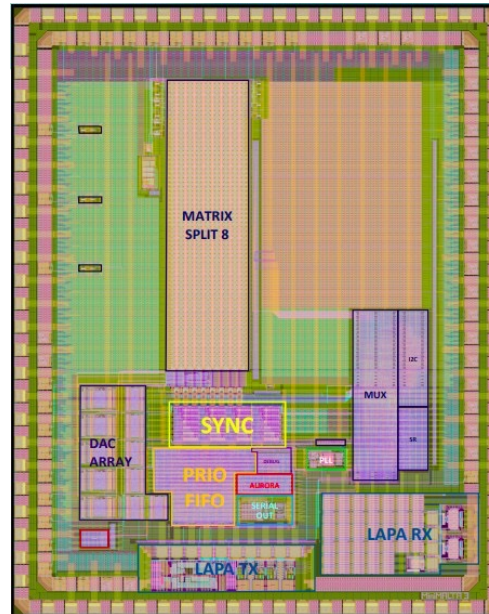
small  
electrode  
(high  
granularity)

Submission	Process	Availability	Target	Comments	Contact Institute	Task Contact
TJ-MALTA 2 /3	TowerJazz 180 nm	Beginning 2021 MPW Q1 2022	High-gran./ Rad. hard Task 5.2/5.3	LHC	CERN	Carlos Solans Sanchez
TJ-Monopix 2 /3 (OBELIX)	TowerJazz 180 nm	Spring 2021 Initiating design	High-granularity Task 5.2	Belle II	Bonn	Jochen Dingfelder
TJ 65	TowerJazz 65 nm	September 2021	High-granularity Task 5.2	Generic R&D / ALICE	IPHC	Jerome Baudot
ARCADIA	LFoundry 110 nm	Summer 2021	High-granularity Task 5.2	Demonstrator chip	INFN	Manuel Rolo
LF-Monopix 2	LFoundry 150 nm	Beginning 2021	Radiation hard Task 5.3	High granularity foreseen	Bonn/CPPM	Marlon Barbero
RD50-MPW 3 /4	LFoundry 150 nm	Spring 2022	High-granularity/ Radiation hard Task 5.3	R&D	Liverpool	Eva Vilella
MiniCactus 23 October 2023	LFoundry 150 nm	Beginning 2021	Radiation hard Task 5.3	Timing R&D	IRFU	Philippe Schwemling

- In the next slides I present a brief overview and latest results for each development line



Mini Cactus 2



RD50-MPW4

- Disclaimer: In AIDA innova the focus is the analog FE and sensor development. Readout aspects are usually too experiment specific and thus are less of a focus in our work



**Tower** 180 nm  
TJ-MALTA-2&3  
TJ-Monopix-2

Goal: large ( $1 \times 2 \text{ cm}^2$  (Malta2)  $\rightarrow$   $3 \times 2 \text{ cm}^2$  (Malta3)) radhard sensor/chip w/ small electrode and high granularity, HL-LHC-layer-5 compatible with low power asynchronous readout architecture. Sensor&FE same as TJ-Monopix.

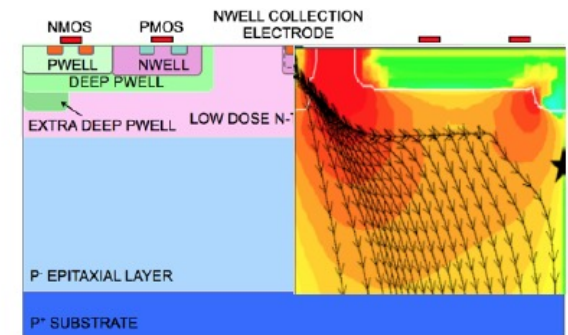
CERN and others (Bonn, CPPM, Oxford ...)  
- 180 nm technology -

- main objective of TJ-MALTA2:

- make design radhard ( $> 1 \times 10^{15} \text{ neq/cm}^2$ ):
  - i. shape charge collection geometry
  - ii. optimize FE against RTS noise
  - iii. use high resistive Cz-Si substrate ( $100 \mu\text{m}$ ) rather than epi-Si ( $25 \mu\text{m}$ ).
- improve asynchronous readout

- objective TJ-MALTA3:

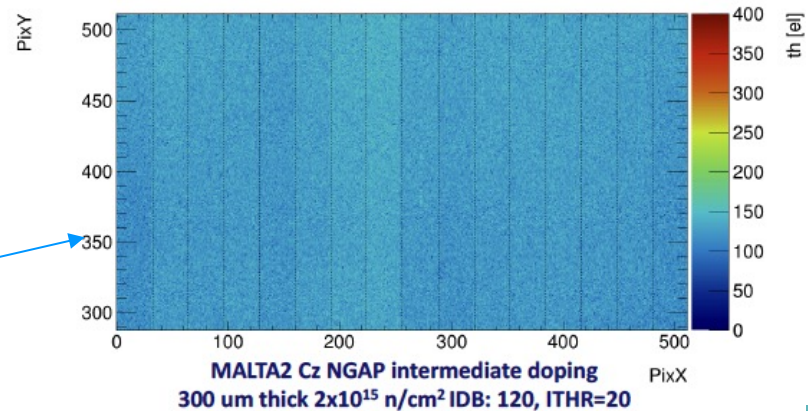
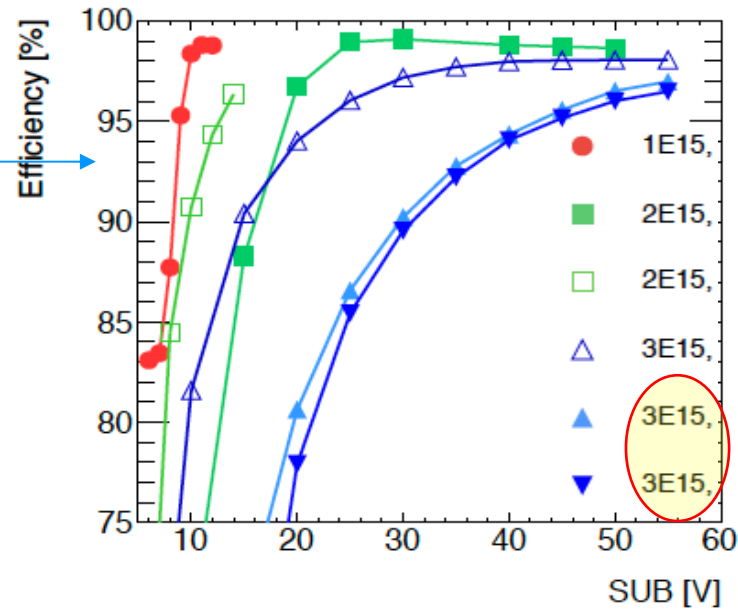
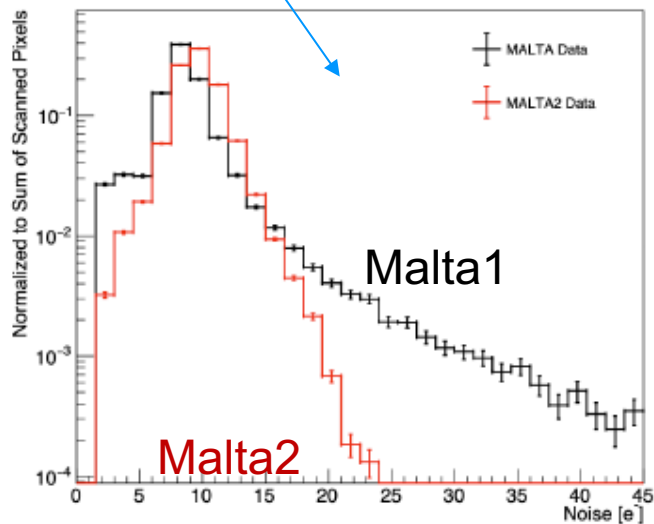
- exploit full reticle size:  $3 \times 2 \text{ cm}^2$
- improve on remaining MALTA2 issues
- add 1.28 GHz local clock
- target: mini-MALTA MPW in Q2 2023



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## Goals of MALTA2 achieved:

- radhard to  $>1\text{E}15$  neq/cm<sup>2</sup>
- @  $3\text{E}15$  neq/cm<sup>2</sup>  $> 95\%$  in 25ns
- RTS noise mitigated



- excellent matrix homogeneity  $2 \times 1$  cm<sup>2</sup>

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## Mini-MALTA3 submitted in June 2023:

- 5x4 mm<sup>2</sup> demonstrator
- 48x64 matrix size of 36.4  $\mu\text{m}^2$
- No clock over the matrix
- Synchronization memory with 0.78 ns time resolution
- Fast clock generation with STFC PLL from 80 MHz clock
- Output data scrambled using Aurora

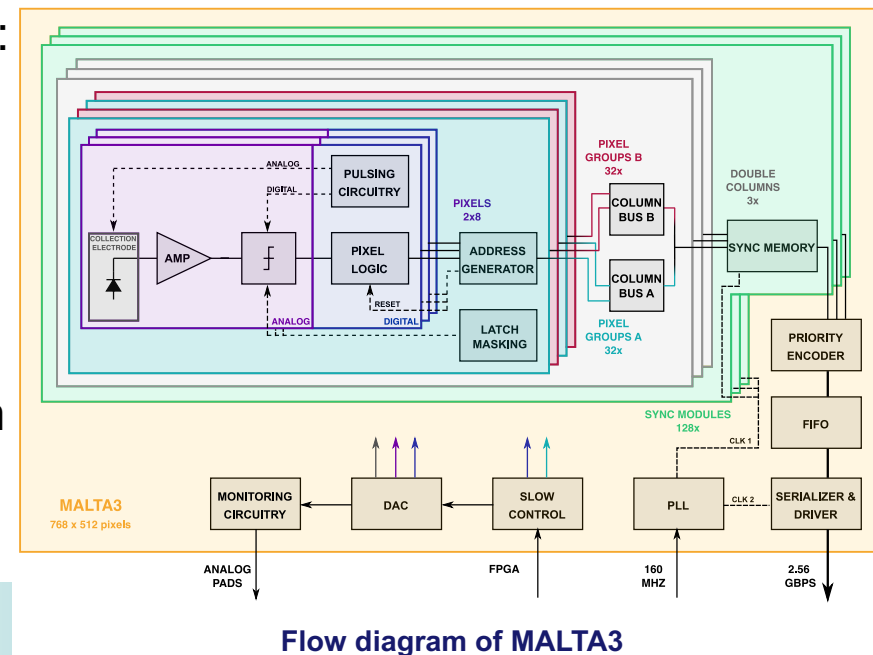


## Full MALTA3 expected to submit Q3 2024:

- Next step in asynchronous read-out architecture
- Full reticle size 3x2 cm<sup>2</sup>
- Asynchronous hit propagation
- Time tagging at end of column
- Add a 1.28 GHz local clock generated from a PLL for time tagging
- Fast read-out with standard protocol

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23 October 2023



Goal: mature large ( $2 \times 2 \text{ cm}^2$ ) high granularity (small electrode) fully functional, HL-LHC compatible (5<sup>th</sup> layer) DMAPS sensor with column drain readout, w/ low noise and low power consumption

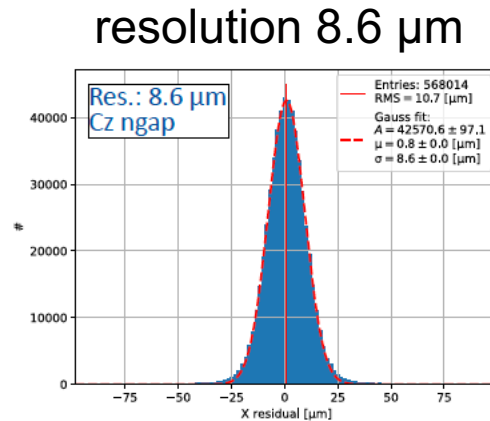
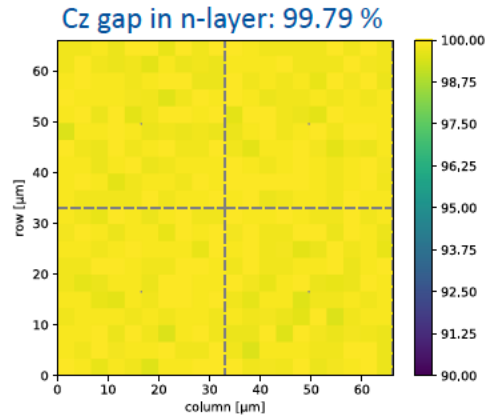
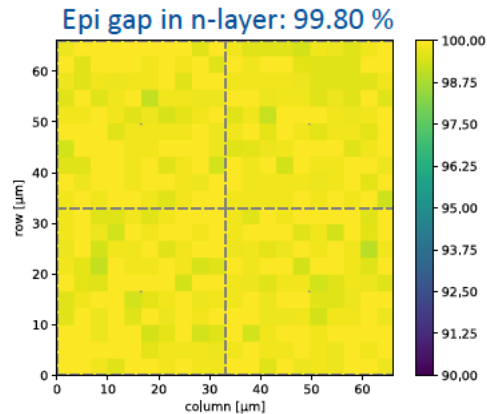
	TJ-Monopix1	TJ-Monopix2
Chip Size	$1 \times 2 \text{ cm}^2$ (224x448 pix)	$2 \times 2 \text{ cm}^2$ (512x512 pix)
Pixel size	$36 \times 40 \mu\text{m}^2$	$33.04 \times 33.04 \mu\text{m}^2$
Total matrix power	$130 \text{ mW/cm}^2$	$170 \text{ mW/cm}^2$
Noise	$\cong 11 \text{ e}^-$	$< 8 \text{ e}^-$ (improved FE)
LE/TE time stamp	6-bit	7-bit
Threshold Dispersion	$\cong 30 \text{ e}^- \text{ rms}$	$< 10 \text{ e}^- \text{ rms}$ (improved FE + tuning)
Minimum threshold	$\cong 300 - 400 \text{ e}^-$	$< 200 \text{ e}^-$
In-time threshold	$\cong 350 - 450 \text{ e}^-$	$< 250 - 300 \text{ e}^-$
Efficiency at $10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ , $30 \mu\text{m}$ epi	$\cong 87 \%$	$> 97 \%$
Efficiency at $10^{15} \text{ n}_{\text{eq}}/\text{cm}^2$ , Cz	$\cong 98.6 \%$	$> 99 \%$

- Clear improvements wrt TJ-M1 before and after irradiation

Bonn, CERN, CPPM, IRFU  
 - 180 nm technology -

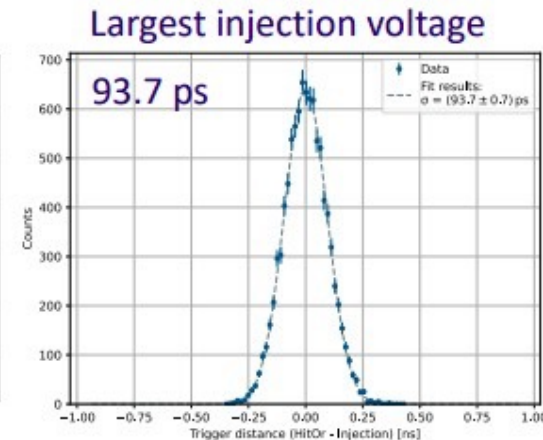
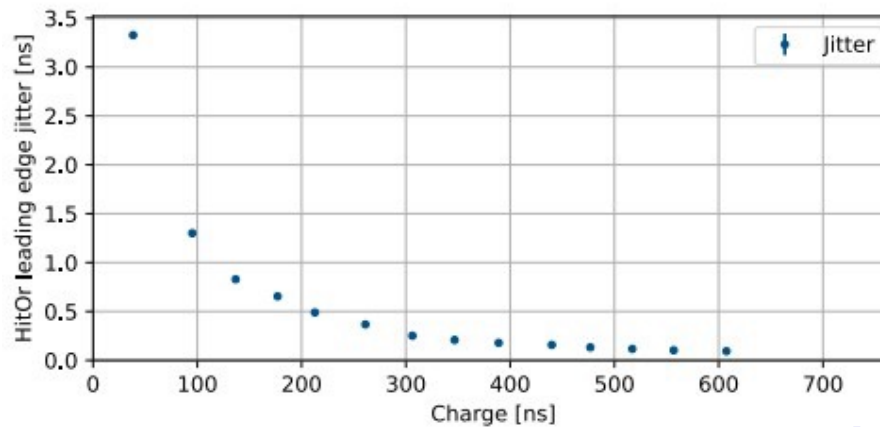
- sensor and chip working
- assembly problems (wire bonding sensibility) reduce yield, is now manageable, but still problematic
- a temporary major problem at 5 MHz BC-ID clock interfering now understood and circumvented
- characterisation finally in full swing
- baseline for Belle II VTX upgrade → Obelix chip:
  - Uses analog part from TJ Monopix 2
  - New digital periphery with several additional features





- very high efficiency (before irradiation)
- irradiation planned Q1/Q2

- Recent timing characterization
- Contribution from jitter (device electronic noise)

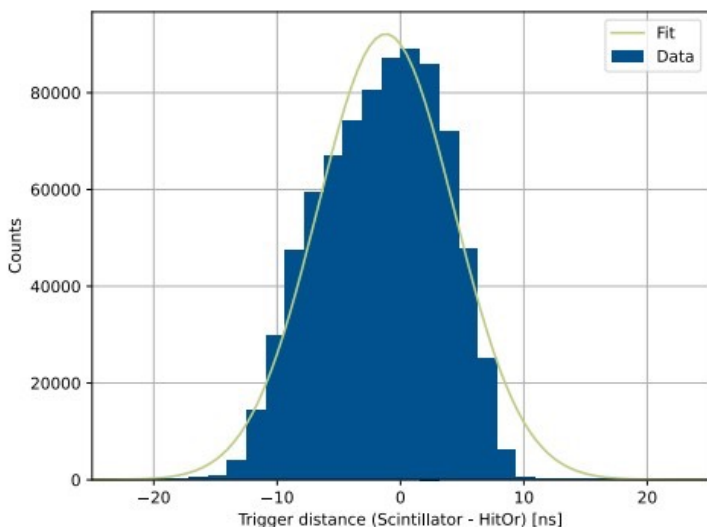


Lab measurement

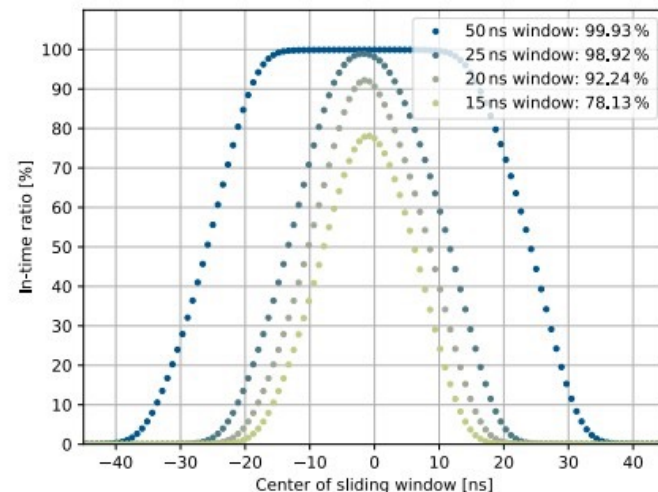
Lars Schall, C. Bepin et al

- In-time ratio: percentage of hits within 25 ns
- Move sliding window over (projected) trigger distance distribution
- 15 ns, 20 ns, 25 ns, 50 ns window width
- **98.92 % for 25 ns window**

	15 ns	20 ns	25 ns	50 ns
<b>Cz normal</b>	78.4 %	92.2 %	98.6 %	99.7 %
<b>Cz cascode</b>	79.2 %	92.3 %	98.2 %	99.7 %
<b>Epi normal</b>	78.1 %	92.2 %	98.9 %	99.9 %
<b>Epi cascode</b>	78.4 %	93.1 %	99.1 %	99.9 %



## Test beam measurement



- Time walk corrected
- Distribution is skewed, matches with time walk curve
- (Bad) fit yields 5.5 ns time resolution
- Trigger scintillator resolution of approx. 1 ns
- **Detector time resolution: 5.4 ns**
  - Detector contribution dominates
  - To investigate other flavors (Cz...)

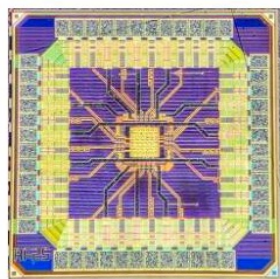
TPSCo 65 nm process of Tower  
(new window of opportunity)

Tower 65nm

Goal: exploring the new technology (large collaboration effort, CERN + 24 institutions) including stitching, .... small electrode designs

1+2 submissions so far: MLR1 (2020), ER1 (2022) each containing several structures and designs

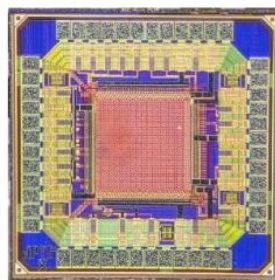
**APTS** Analogue Pixel Test Structure



**Matrix:** 6x6  
**Readout:** analogue readout of 4x4  
**Pitch:** 10, 15, 20, 25  $\mu\text{m}$   
**Process:** all 3 variants

1.5 mm

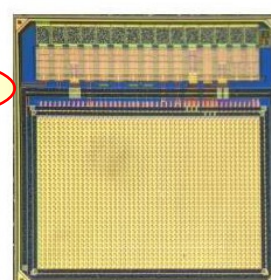
**DPTS** Digital Pixel Test Structure



**Matrix:** 32x32  
**Readout:** async. digital with ToT  
**Pitch:** 15  $\mu\text{m}$   
**Process:** 1 variant (modified with gap process)

1.5 mm

**CE-65** Circuit Exploratoire 65

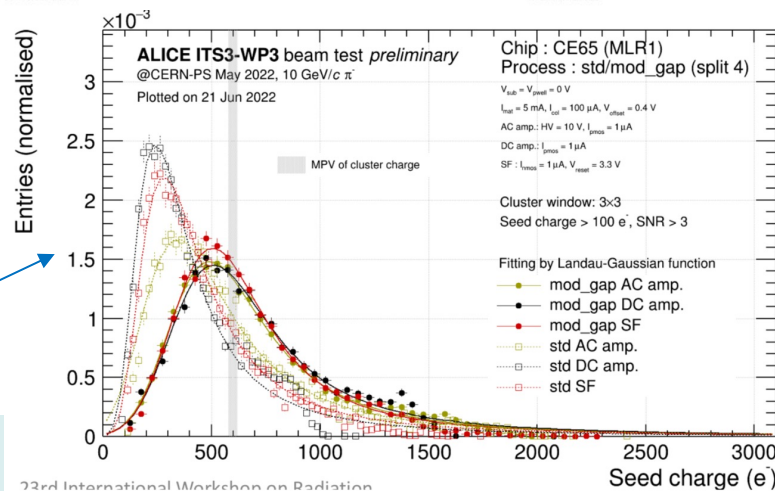


**Matrix:** 48x32  
**Readout:** rolling shutter analog  
**Pitch:** 15, 25  $\mu\text{m}$   
**Process:** 1 variant (modified with gap process)

1.5 mm

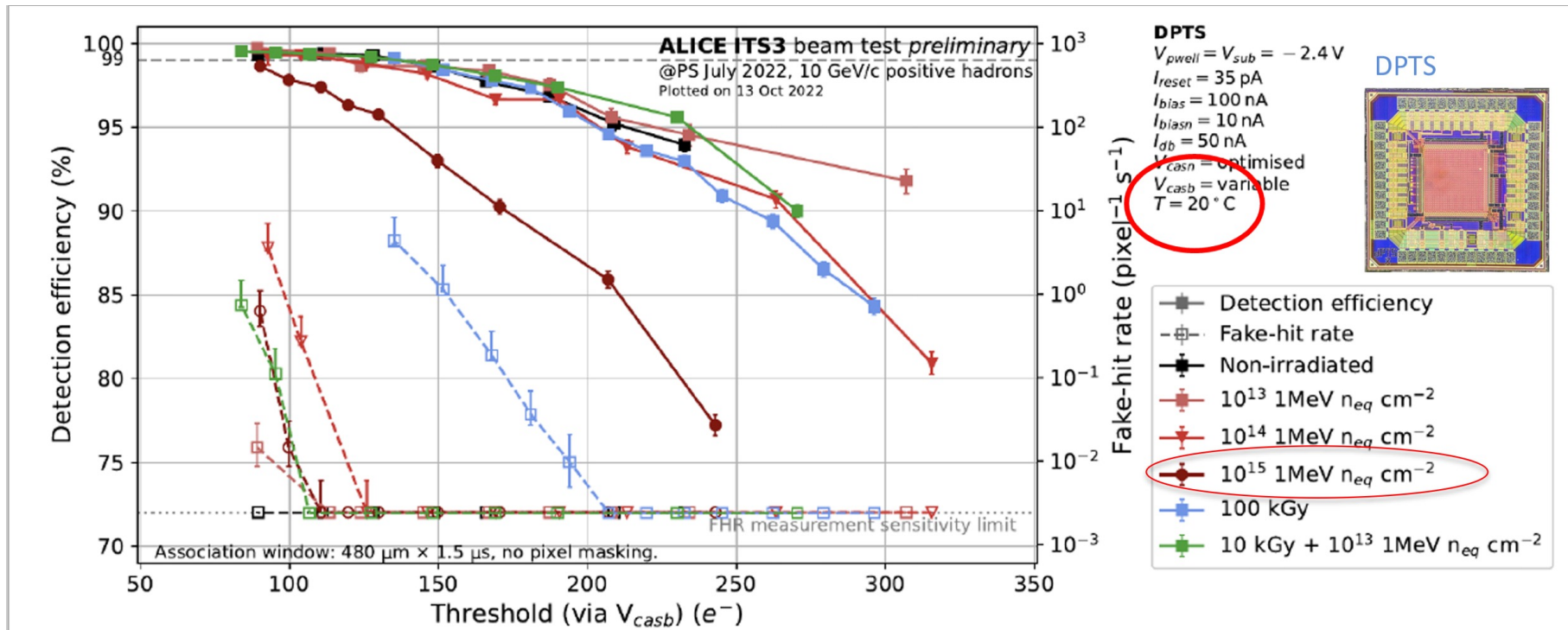
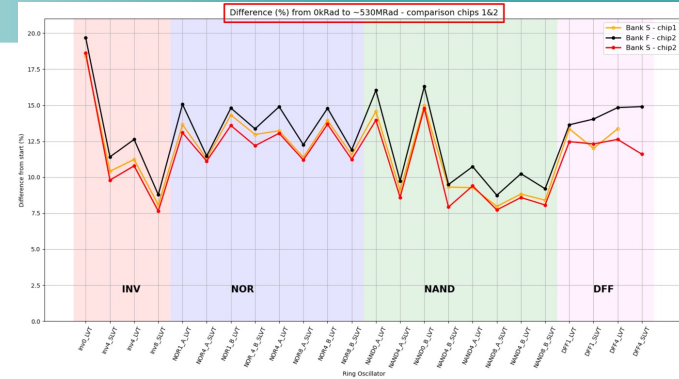
from MLR1

promising results from MLR1  
leakage cur. ✓  
Testbeam with DPTS (digital 15  $\mu\text{m}$ ) proved that process modification works



Promising radiation tolerance:

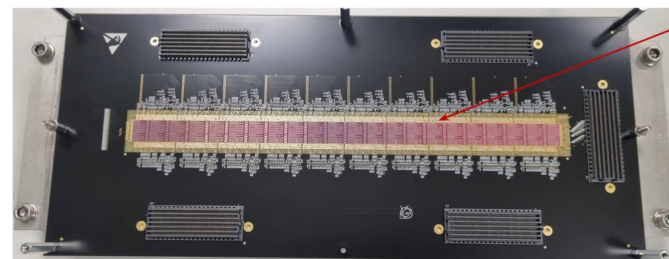
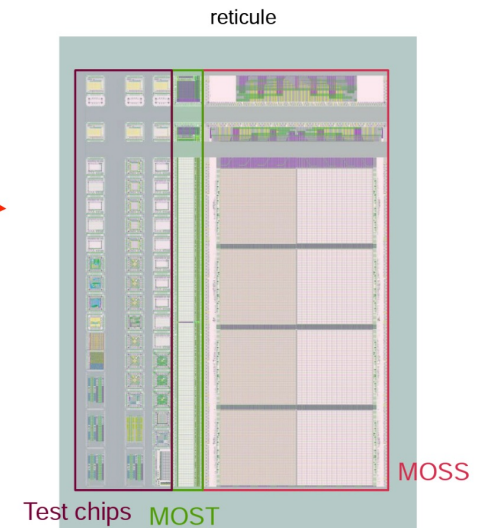
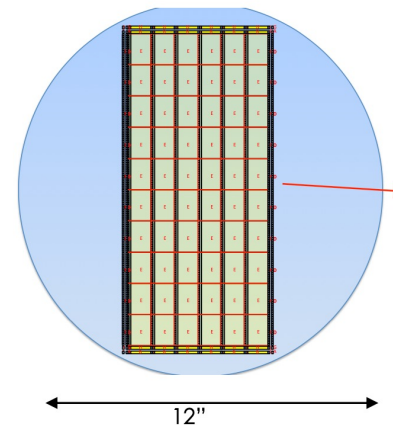
- DPTS (digital) with 15  $\mu\text{m}$  pitch
- Beam test results
- also for digital cells as shown with TID measurements on ring oscillators





## 2<sup>nd</sup> submission: Engineer Run 1 (ER1)

- Main goal = exercise stitching (in 1D) to assess yield
- Submission November 2022
- Back from fab April 2023
- 2 long (~26 cm) sensors
  - **MOSS**: priority-encoder readout (ALPIDE-like)
    - 1.4 cm wide
    - 18 & 22.5  $\mu\text{m}$  pitch
  - **MOST**: low power asynchronous readout
    - 0.25 cm wide
- Many (51) **chiplets**
  - Pixel prototypes
  - SEU test chips
  - Functional blocks (PLL, serial links)
- New metal staks
- New methodology for submission
  - Digital-on-top



wafer-scale  
dummy sensor

Test in preparation

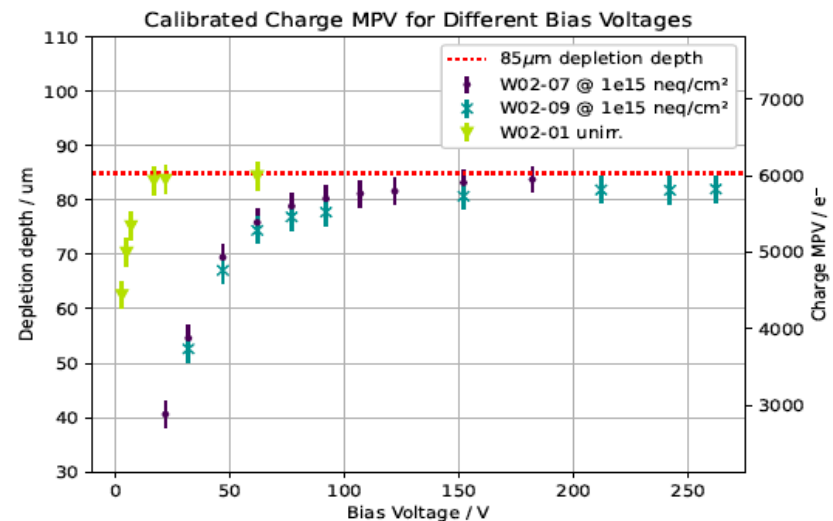
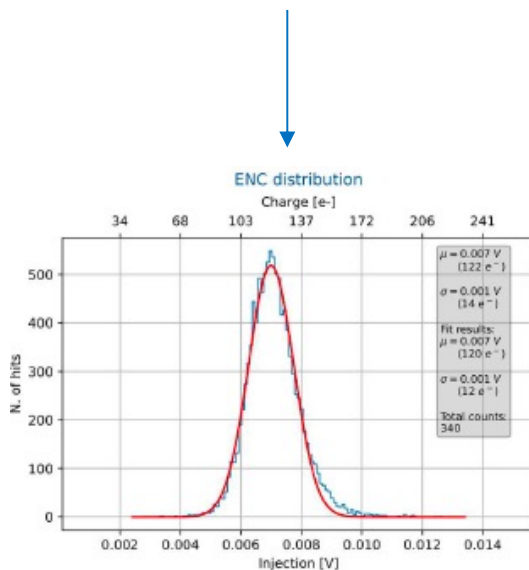
LFfoundry 150 nm

- LF-Monopix-2
- RD50 – MPW2/3
- CACTUS

Goal: mature large ( $1 \times 2 \text{ cm}^2$ ) (very) radhard, large electrode fully functional, HL-LHC compatible (5<sup>th</sup> layer) DMAPS sensor with column drain readout

irradiated devices ( $1 \text{e}15 \text{ n}_{\text{eq}}/\text{cm}^2$  @ Bonn Cyclotron)

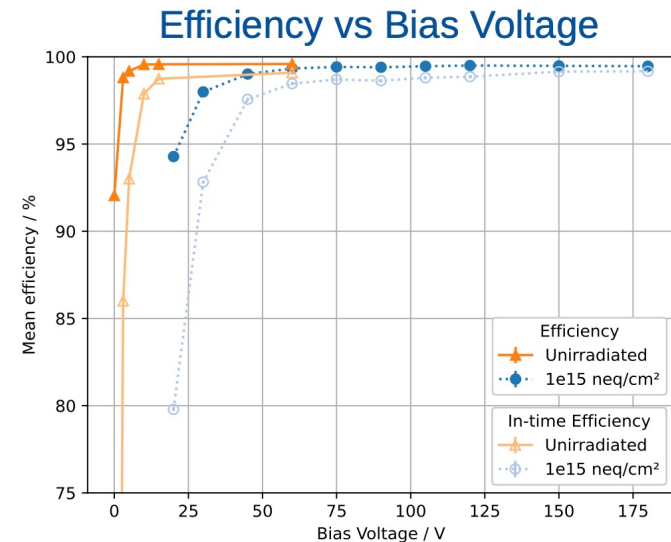
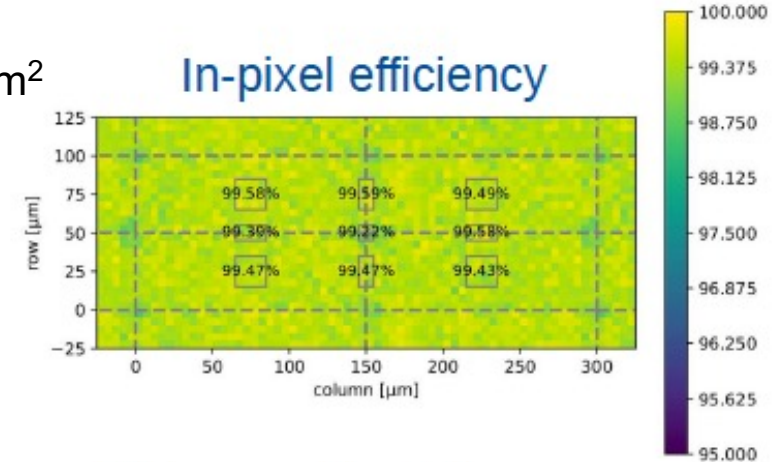
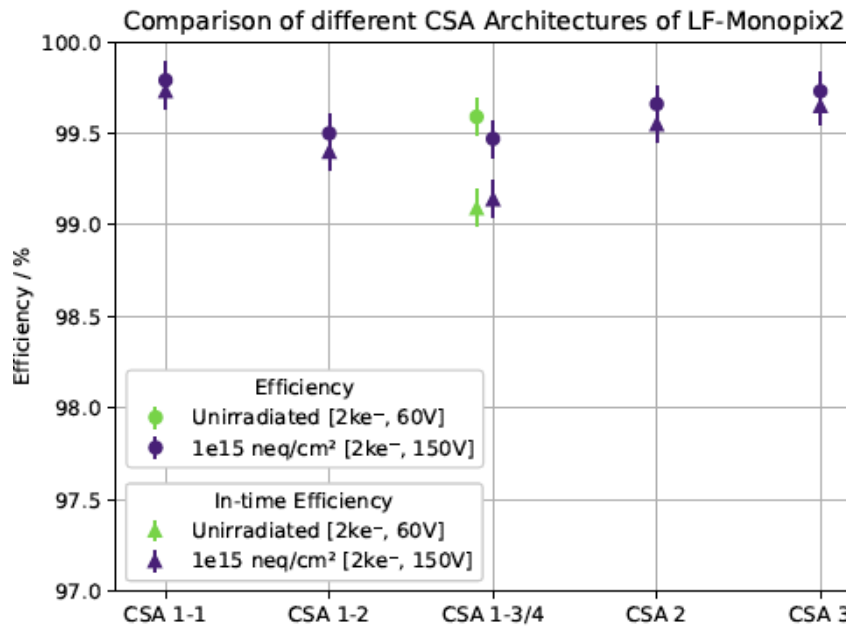
- no significant degradation at this level except for leakage current increase



Lars Schall, C. Bepin, et al.

- fully depleted @ 100 V bias (15 V unirr.)

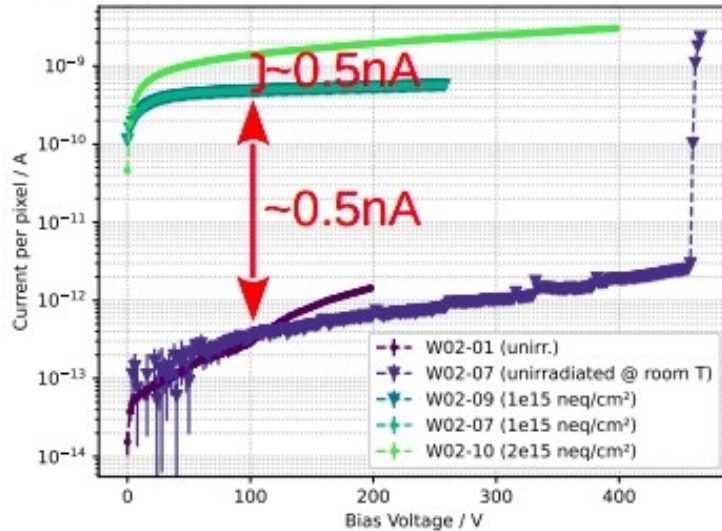
- intensive test beam characterisation
- very high (>99%) efficiency (in-time) after  $1e15 \text{ n}_{\text{eq}}/\text{cm}^2$
- ~no efficiency degradation w.r.t. unirradiated devices



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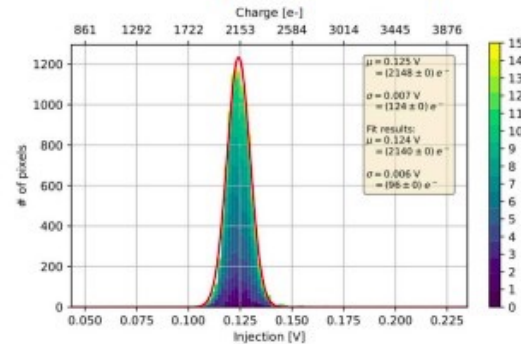
Recently exploring **the radiation hardness limit** by going from  $1e15 \text{ n}_{eq}/\text{cm}^2 \rightarrow 2e15 \text{ n}_{eq}/\text{cm}^2$

### I-V curve comparison @ different fluences

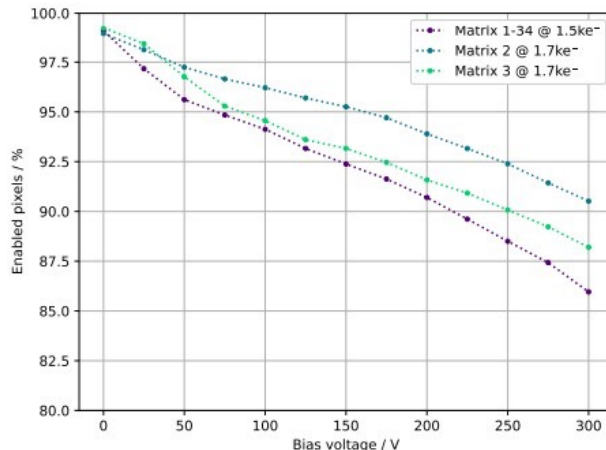
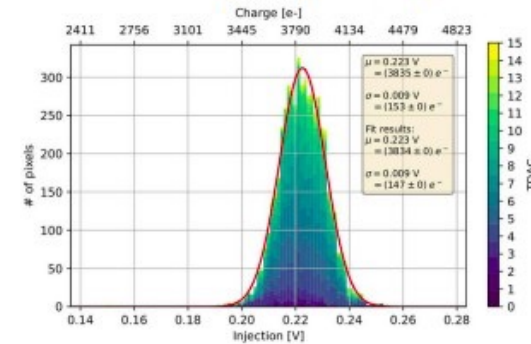


- High noise increase observed:
  - Unirr @ -40V bias ( $\sim 90e$ )
  - $1e15$  @ -150V bias ( $120e$ )
  - $2e15$  @ -250V bias ( $\sim 170e$ )
- Difficult to reach low threshold for stable operation

### $1e15 \text{ n}_{eq}/\text{cm}^2$ (W02-07)



### $2e15 \text{ n}_{eq}/\text{cm}^2$ (W02-10)



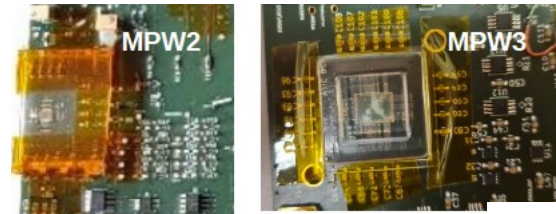
- Challenging to operate chip at such high radiation level
  - missing leakage current compensation
  - beyond original target of outer tracking layer
- Studies on-going ...



**Goal:** series of MPWs (1 ... 4) to achieve very small pixels ( $60 \times 60 \mu\text{m}^2$ ) radhard @ HL-LHC level 5<sup>th</sup> layer by large electrode design (all electronics inside deep well)

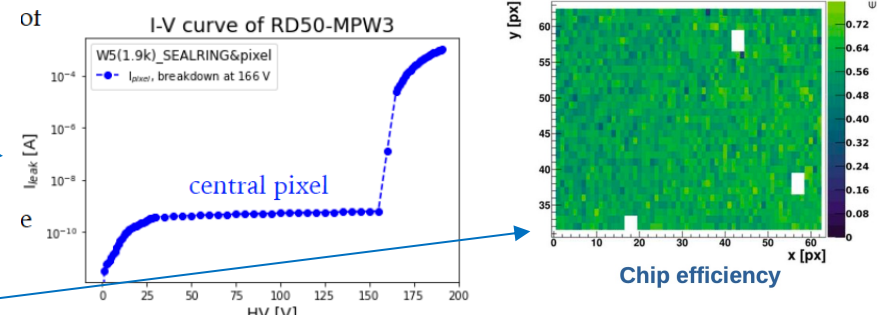
**MPW2:** small prototype

- pixels:  $60 \times 60 \mu\text{m}^2$
- in-pix CSA + discriminator, analog R/O
- testbeams performed
- charge collection ok



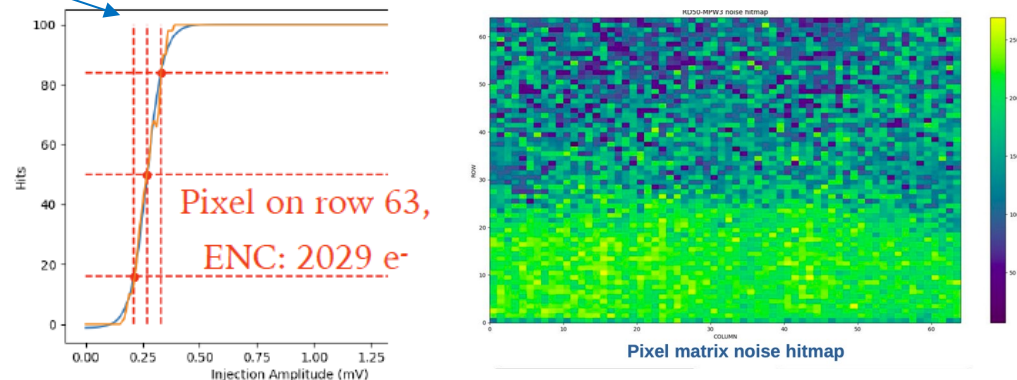
**MPW3:** added digital R/O (column drain)

- $V_{\text{breakdown}} \sim 150\text{V}$
- very high noise ( $> 2000 \text{ e}$ ) due to noise coupling from digital periphery
- Poor test beam efficiency due to high thresholds



**MPW4** (sub. May 2023):

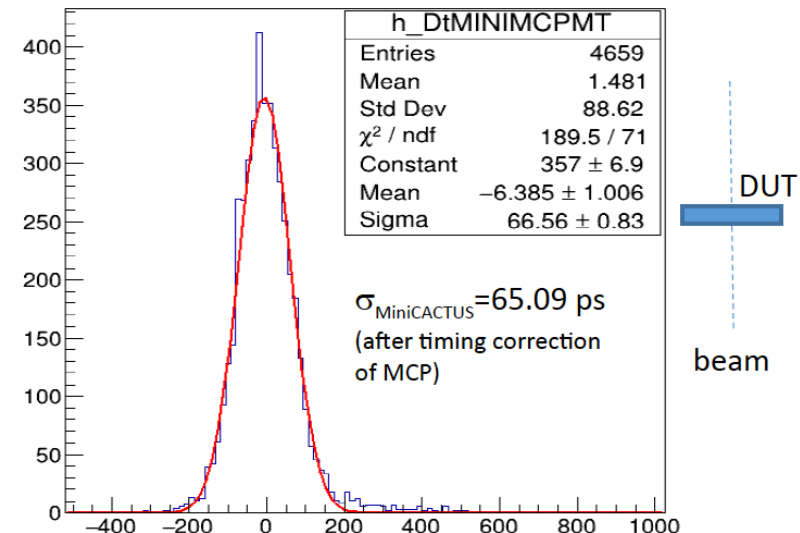
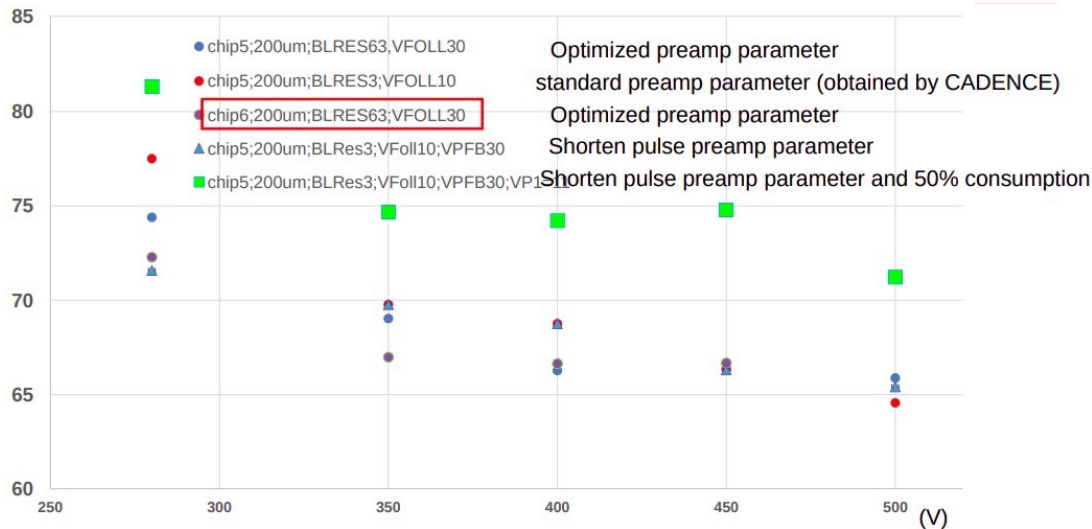
- backside processing to improve radiation hardness
- Address noise limitation of MPW3 by separate power domains of pixel matrix and periphery



Goal: Develop CMOS pixels for timing applications ( $\sim 50$  ps)

Mini CACTUS = small prototype to address limitations of CACTUS (low S/N) in LFoundry 150nm

- **65 ps mip time resolution achieved** in test beams for unirradiated devices
- compared calibrations and resolutions using photons of different energies ( $^{241}\text{Am}$  and @SOLEIL)
  - calibrations ✓
  - $\sigma_t$  for photons (understandably) worse (320 ps)



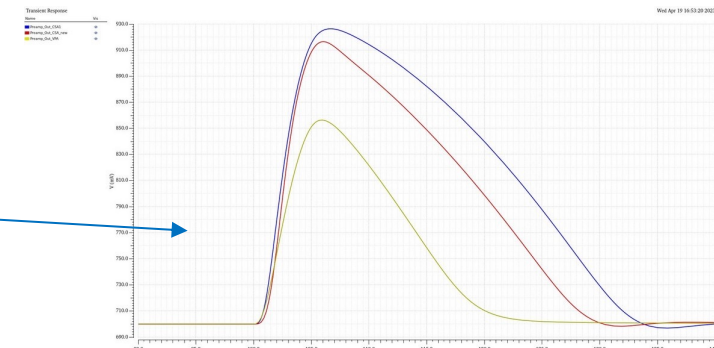
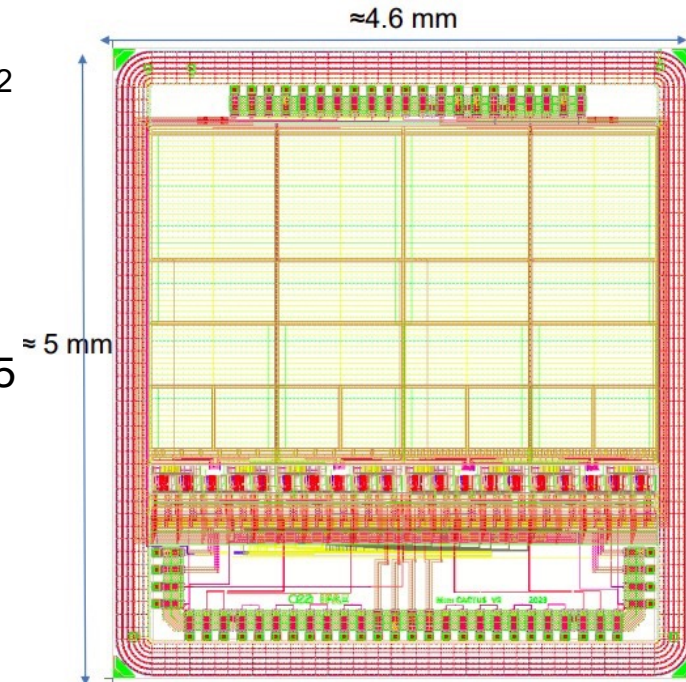
P. Schwemling, Y. Degerli et al

## Next:

- characterisation after  $1e14$ ,  $1e15$ , and  $1e16$  neq/cm<sup>2</sup>
- new Mini-CACTUS submission May 2023, back December 2023

## Mini-CACTUS2:

- ~ 2 times larger than Mini-CACTUS
- 0.5 mm x 1 mm (baseline), 1 mm x 1 mm and 0.5 mm x 0.5 mm diodes
- 50  $\mu$ m x 150  $\mu$ m and 2 50  $\mu$ m x 50  $\mu$ m small test diodes
- 3 different preamps
- New multistage discriminator with **programmable hysteresis**
- Improved layout for better mixed-signal coupling rejection
- **CEA-IRFU & IFAE-Barcelona** coll.
- Expect better timing performance from simulation ...



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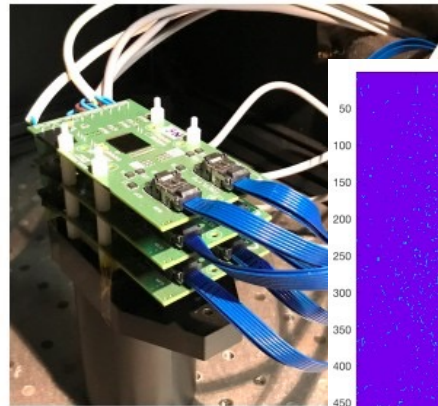
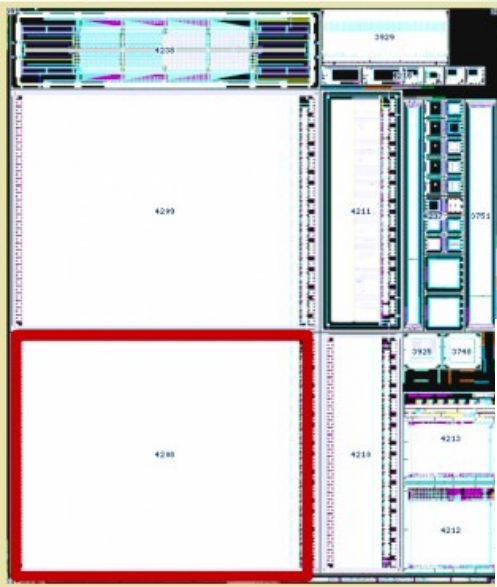
LFfoundry 110 nm  
**ARCADIA**



Goal: Develop DMAPS technology platform in 110 nm technology. Largely funded by INFN. Targeting small pixels, very low power, various thicknesses

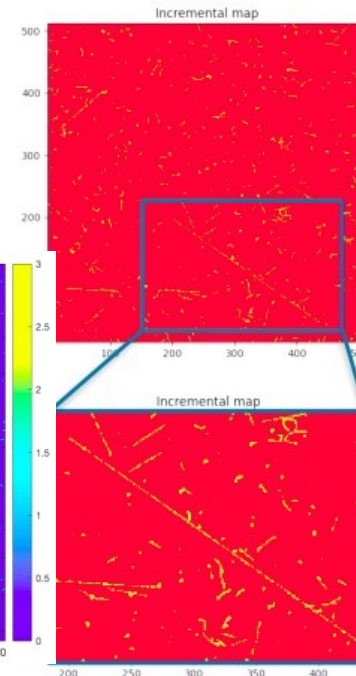
- 110nm CMOS node (quad-well, both PMOS and NMOS), high-resistivity bulk
- Custom patterned backside, patented process developed with LFoundry

- ARCADIA-MD3 Demonstrator
- Included several structures/chips
  - Pixel down to 10  $\mu\text{m}$
  - ASIC for strip r/o
  - X-ray counter
  - Timing detector
  - ...

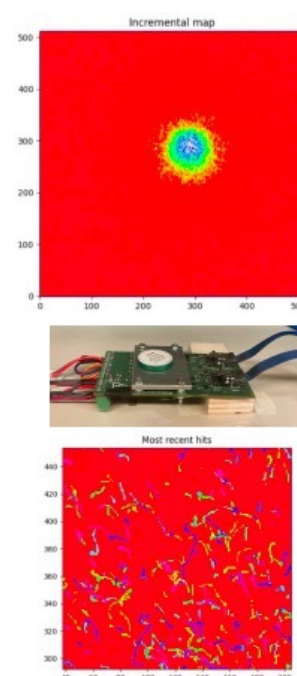


CR tests:  
telescope

Cosmic rays  
(tilted sensor)



$^{90}\text{Sr}$   
(collimated 1mm)

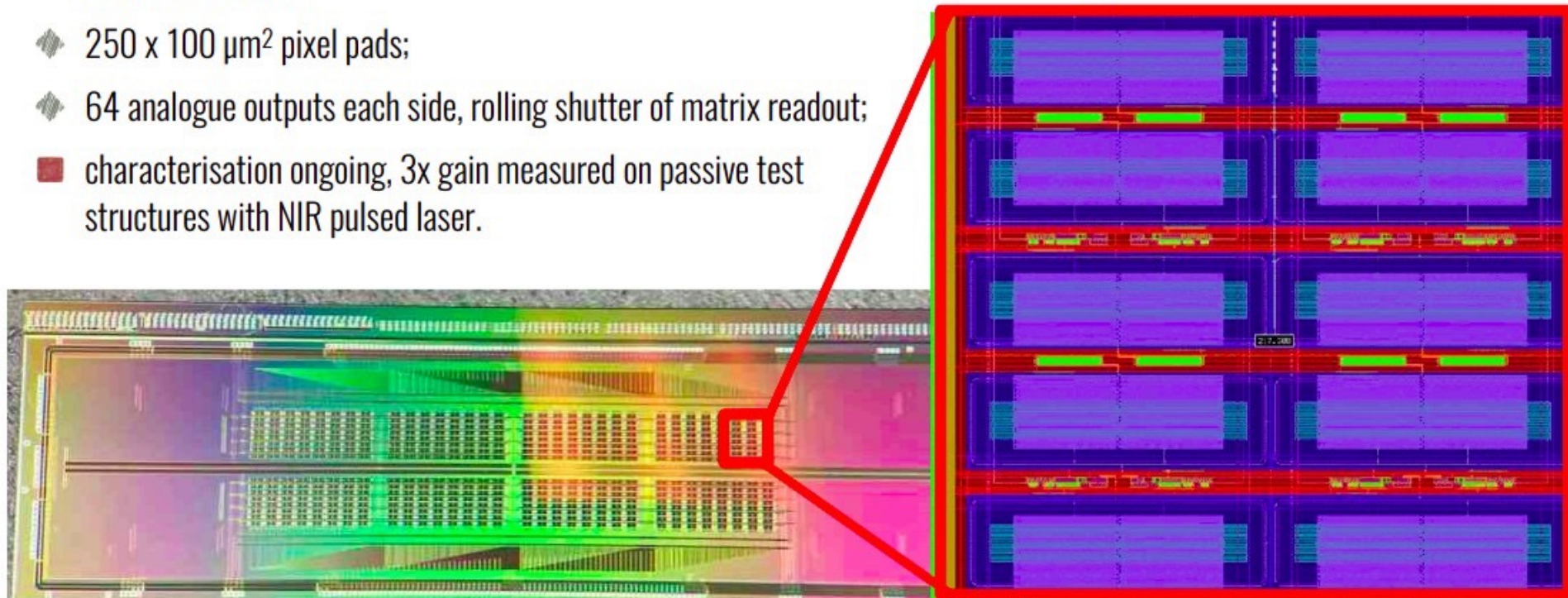
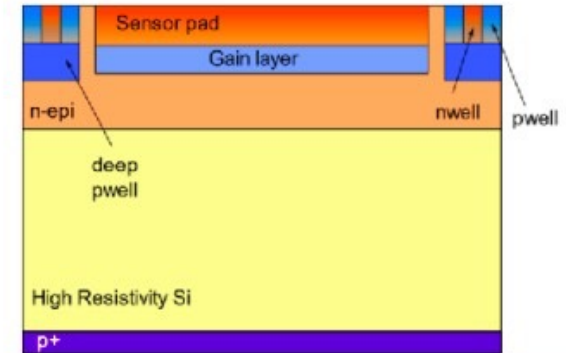


23 October 2023



### Timing detector

- ◆ partial lot of HR and p+ wafer splits implement an extra **gain layer** added to the sensor;
- ◆ first small-scale demonstrator 4 x 16 mm<sup>2</sup>;
- ◆ 8 matrices (64 pixel pads each) implementing different sensor and front-end flavours;
- ◆ 250 x 100 μm<sup>2</sup> pixel pads;
- ◆ 64 analogue outputs each side, rolling shutter of matrix readout;
- characterisation ongoing, 3x gain measured on passive test structures with NIR pulsed laser.



- AIDAinnova contributes significantly to DMAPS developments for future HEP experiments
- Many different projects targeting different requirements such as high resolution, high radiation tolerance, fast timing and fast readout
- Very good results on all fronts and we expect more in the next two years of AIDAinnova

## TJ-MALTA

- JINST 2021 <https://doi.org/10.5281/zenodo.6951327>
- TWEPP 2021 <https://doi.org/10.1088/1748-0221/17/04/C04034>
- IEEE TNS 2022 <https://doi.org/10.1109/TNS.2022.3170729>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167390>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167226>
- NIM A 2023 <https://doi.org/10.1016/j.nima.2022.167809>
- EPJ-C 2023 <https://doi.org/10.1140/epjc/s10052-023-11760-z>
- JINST 2023: <https://doi.org/10.1088/1748-0221/18/03/C03011>
- JINST 2023: <https://doi.org/10.1088/1748-0221/18/03/C03013>

## TJ-Monopix

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167189>
- arXiv 2023 <https://doi.org/10.48550/arXiv.2301.13638>

- 18 publications so far
- More to come

## LF-Monopix

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167224>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.166747>

## CACTUS

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167022>

## TJ 65nm

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167213>

## RD50-MPW

- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.166826>
- NIM A 2022 <https://doi.org/10.1016/j.nima.2022.167020>
- JINST 2023 <https://doi.org/10.1088/1748-0221/17/12/C12017>

## WP5 meetings at:

<https://indico.cern.ch/category/13503/>